







Onboard Plate OGP-2520,0GP-3216, OGP-4520

NFW



OGP configuration ensures reliable contact



- OGP solves contact failure problems caused by solder flux
- Better reliability compared with solder
- Eliminates continuity failure caused by pattern scraping between a PCB and pogo pins and a PCB and a metal plate
- OGP-2520 is 40 % or more downsized from OGP-4520. (Product size: 2.5 mm)
- Gold-plated OGP-3216 can be used as a partial gold plating on PCBs

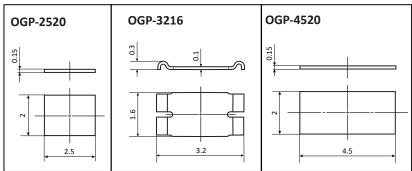
Dimensions

Material

Base material: Brass

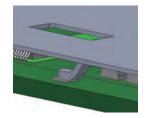
Surface treatment: Sn reflow plating *(First plating: Cu plating)

*Surface treatment for OGP-3216: Au/Ni plating on both sides



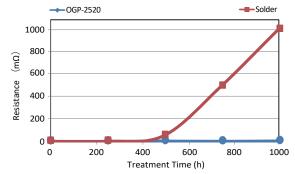
Application examples





Screw loosening prevention and automated mounting

Resistance Measurement Results



Treatment condition: 125℃

Test method:

- ①A terminal and OGP-2520s are soldered on a substrate.

 A second terminal is soldered on to a separate substrate, with solder fillets applied on the substrate at the same position as the OGP.
- ②A screw is tightened in each location and the substrates are heat treated.
- ③After the treatment, the resistance between the terminal and screw is measured with a Milliohm HiTester.





	Washers	OGP Series
Mounting Method	Manual	Automated

- Cost saving by automation!
- Parts are automatically counted by mounters.



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